


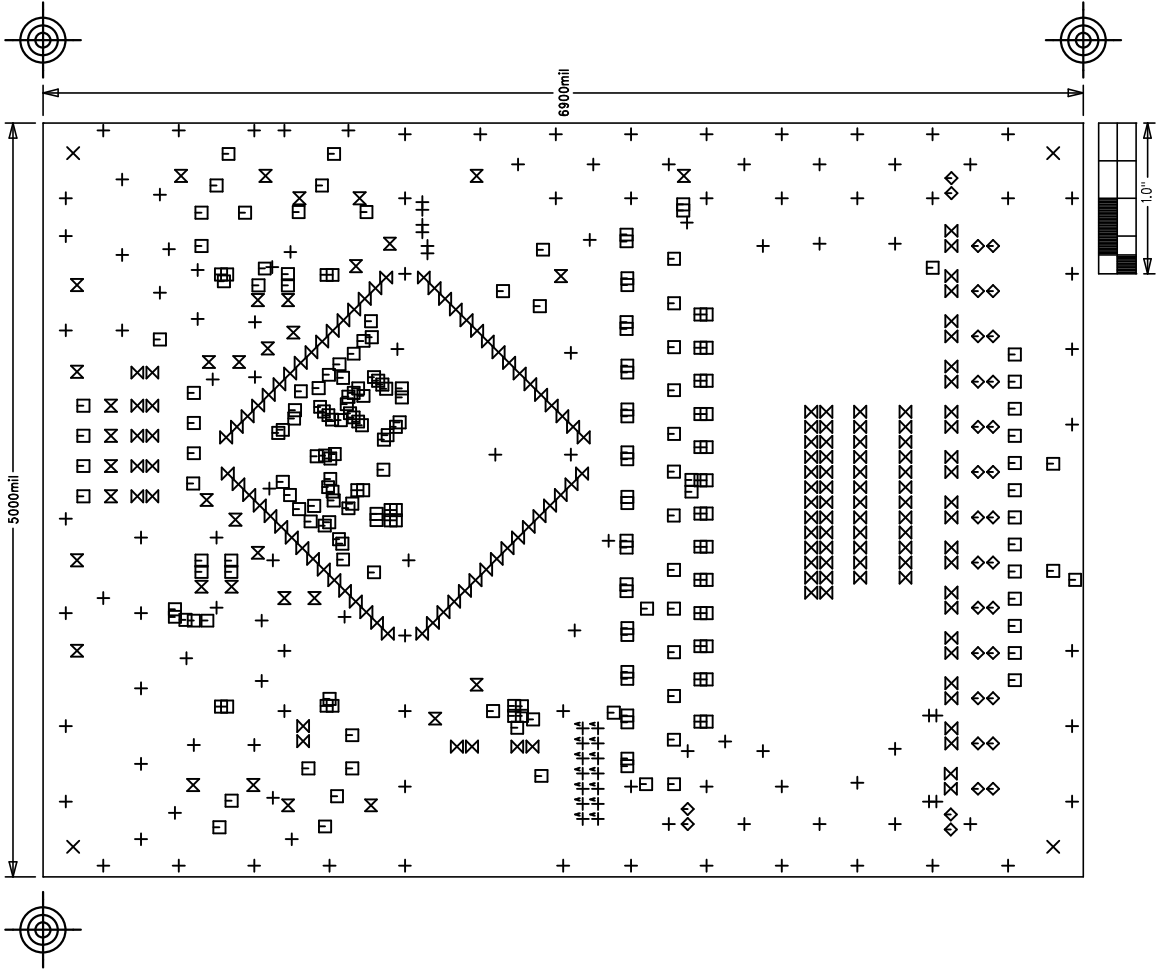
MAX17823 EVKIT

REV
A

 **maxim**
integrated™

LAYER
DRILL & MECHANICALS

DATE:
ALL UNITS ARE IN 0.001"



NOTES: UNLESS OTHERWISE SPECIFIED

1. FABRICATE USING PROVIDED GERBER FILES PER LATEST REVISION OF IPC-A-600 UNLESS OTHERWISE NOTED.
2. MATERIAL: ROHS COMPLIANT FR-408 OR SIMILAR LAMINATE MATERIAL WITH Tg>=170 AND COMPATIBLE WITH LEAD-FREE SOLDERING PROCESS.
3. BOARD DIMENSIONS: 5.00"x6.90" +/- 0.010".
4. BOARD THICKNESS: 0.062"
5. LAYERS: 4. SEE LAYER STACKUP CHART.
6. MINIMUM TRACE/SPACING: 10 MILS/8MILS.
7. COPPER CLAD FINISH: 1oz MIN ON OUTER LAYERS AND 1/2oz ON INNER LAYERS.
8. SURFACE MOUNT PADS: 619.
9. SOLDERMASK: GREEN LPI SMOBC.
10. LEGENDS: WHITE, DOUBLE-SIDED, NON-CONDUCTIVE EPOXY INK OR EQUIVALENT. CLIPPED ALL LEGENDS FROM EXPOSED METAL.
11. PLATING: MUST BE LEAD FREE AND ROHS COMPLIANT.
12. FINISH: VENDOR SHOULD USE THE MOST ECONOMICAL LEAD FREE AND ROHS COMPLIANT PROCESS AVAILABLE OR AS SPECIFIED IN PURCHASE ORDER.

APPROVED FINISH:
HASL LEAD-FREE
IMMERSION TIN
IMMERSION GOLD

12. VENDOR LOGO & DATE CODE REQUIRED IN INK ON BOTTOM SIDE ONLY. DATE CODE FORMAT MUST BE YYWW ONLY
13. THRU HOLES: 0.001" MIN.
14. TOLERANCES:
PLATED-THRU HOLES: +/-0.003"
PATTERN-TO-PATTERN: +/-0.005"
LEGEND TO LEGEND: +/-0.007"
SOLDERMASK TO PATTERN: +/-0.005"

LAYER 1 TOP	1.4MIL
LAYER 2 GND	PRE-PREG AS NEEDED
LAYER 3 POWER/GND	CORE AS NEEDED
LAYER 4 BOTTOM	PRE-PREG AS NEEDED

ALL DIMENSION IN MIL (0.001 INCH) UNLESS OTHERWISE SPECIFIED.

SIZE	QTY	SYM	PLATED	TOL
15	215	□	YES	+/-3
25	129	+	YES	+/-3
37	156	⊗	YES	+/-3
39	14	⊕	YES	+/-3
40	32	◇	YES	+/-3
67	36	⊗	YES	+/-3
125	4	⊗	YES	+/-3